

We claim:

1. A printed circuit board formed by the process comprising:

forming a conductor core containing a thin base of electrically conductive material and areas of thick conductive material in a predetermined pattern;

bonding the conductor core to a sublayer of electrically insulating material to create a flat laminate, wherein the areas of thick conductive material are positioned adjacent to the sublayer; and,

forming predetermined printed circuits by removing conductive material from the flat laminate that does not comprise said predetermined printed circuits to form the predetermined printed circuits.

2. The printed circuit board of claim 1 wherein the conductor core and predetermined printed circuits comprise copper.

3. The printed circuit board of claim 1 wherein forming of the conductive core further comprises electrolytically depositing the areas of thick electrically conductive upon the thin electrically conductive base.

4. The printed circuit board of claim 1 wherein the sublayer of electrically insulating material comprises sheets of glass fiber reinforced with resin that is dried but not cured.

5. The printed circuit board of claim 4 wherein the bonding of the conductor core to conductor core to the sublayer.

6. The printed circuit board of claim 5 wherein the hot pressing is performed at sufficient temperature and for a sufficient period of time to enable full and complete curing of the resins in the insulating sublayer.

7. The printed circuit board of claim 1 wherein removing of conductive material is accomplished through chemical etching.

8. The printed circuit board of claim 1 further comprising applying a solder mask coating over predetermined areas of the printed circuit board.

9. The printed circuit board of claim 1 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0020 inches.

10. The printed circuit board of claim 1 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0007 inches.

11. The printed circuit board of claim 1 wherein said areas of thick conductive material are of a thickness in the range of 0.004 inches to 0.020 inches in predetermined pattern of conductor traces.

12. The printed circuit board of claim 1 wherein said areas of thick conductive material are of a thickness in the range of 0.004 inches to 0.010 inches in a predetermined pattern of conductor traces.

13. A printed circuit board formed by the process comprising:

forming a conductor core containing a thin base of electrically conductive material and areas of thick conductive material in a predetermined pattern;

bonding the conductor core to an inner layer of resinous material and a sublayer of electrically insulating material to create a flat laminate, wherein the areas of thick conductive material are positioned adjacent to the inner resinous material layer that is in turn positioned adjacent to the sublayer of insulating;

said layer of resinous material selected from a group of resinous materials that is compatible with the sublayer of electrically insulating material and;

removing conductive material from the flat laminate that does not comprise said predetermined printed circuits to form a predetermined printed circuit.

14. The printed circuit board of claim 13 wherein the conductor core and predetermined printed circuits comprise copper.

15. The printed circuit board of claim 13 wherein forming of the conductive core further comprises electrolytically depositing the areas of thick electrically conductive upon the thin electrically conductive base.

16. The printed circuit board of claim 13 wherein the sublayer of electrically insulating material comprises sheets of glass fiber reinforced with resin that is dried but not cured.

17. The printed circuit board of claim 16 wherein the bonding of the conductor core to the sublayer of electrically insulating material comprises hot pressing the conductor core to the sublayer.

18. The printed circuit board of claim 17 wherein the hot pressing is performed at complete curing of the resins in the insulating sublayer.

19. The printed circuit board of claim 13 wherein removing of conductive material is accomplished through chemical etching.

20. The printed circuit board of claim 13 further comprises applying a solder mask coating over predetermined areas of the printed circuit board.

21. The printed circuit board of claim 13 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0020 inches.

22. The printed circuit board of claim 13 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0007 inches.

23. The printed circuit board of claim 13 wherein said areas of thick conductive material are in the range of 0.004 inches to 0.020 inches in a predetermined pattern of conductor traces.

24. The printed circuit board of claim 13 wherein said areas of thick conductive material are in the range of 0.004 inches to 0.010 inches in a predetermined pattern of conductor traces.

25. A printed circuit core suitable for use as a component of a multilayer printed circuit formed by the process comprising:
forming a conductor core comprising a thin base of electrically conductive material and areas of thick conductive material in a predetermined pattern;
bonding the conductor core to a sublayer of electrically insulating material creating a flat laminate, wherein the areas of thick conductive material are positioned adjacent to the sublayer; and;
removing conductive material from the flat laminate that does not comprise said predetermined printed circuits thereby forming predetermined printed circuits.

26. The printed circuit core of claim 25 wherein the conductor core and predetermined printed circuits comprise copper.

27. The printed circuit core of claim 25 wherein forming of the conductive core further comprises electrolytically depositing the areas of thick electrically conductive upon the thin electrically conductive base.

28. The printed circuit core of claim 25 wherein the sublayer of electrically insulating material comprises sheets of glass fiber reinforced with resin that is dried but not cured.

29. The printed circuit core of claim 28 wherein the bonding of the conductor core to the sublayer of electrically insulating material is performed by hot pressing the conductor core to the sublayer.

30. The printed circuit core of claim 29 wherein the hot pressing is performed at sufficient temperature and for a sufficient period of time to enable full and complete curing of the resins in the insulating sublayer.

31. The printed circuit core of claim 25 wherein removing of conductive material is accomplished through chemical etching.

32. The printed circuit core of claim 25 wherein said thin base is of a thickness in

the range of 0.0003 inches to 0.0020 inches.

33. The printed circuit core of claim 25 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0007 inches.

34. The printed circuit core of claim 25 wherein said areas of thick conductive material are in the range of 0.004 inches to 0.020 inches in a predetermined pattern of conductor traces.

35. The printed circuit core of claim 25 wherein said areas of thick conductive material are in the range of 0.004 inches to 0.010 inches in a predetermined pattern of conductor traces.